

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1-28. (Cancelled)

29. (Currently Amended) A semiconductor package, comprising:

a leadframe having:

a homogeneous die pad defining opposed upper and lower surfaces; and

a plurality of homogeneous bonding pads disposed at least partially about the die pad in spaced relation thereto, each of the bonding pads defining opposed upper and lower surfaces;

a die attached to the upper surface of the die pad and electrically connected to at least one of the bonding pads; and

a molding compound at least partially encapsulating the die and the leadframe such that portions of the bonding pads **and the die pad** which define the lower surfaces thereof protrude from a lower surface of the molding compound;

wherein the leadframe is subjected to a metal removal process which electrically isolates the bonding pads and the die pad from each other, and exposes the lower surface of the molding compound.

30. (Previously Presented) The semiconductor package of Claim 29 wherein the die is attached to the upper surface of the die pad through the use of an adhesive material.

31. (Previously Presented) The semiconductor package of Claim 30 wherein the adhesive material comprises an epoxy.

32. (Previously Presented) The semiconductor package of Claim 29 wherein the die is electrically connected to the bonding pads via bonding wires which are encapsulated by the molding compound.

33. (Previously Presented) The semiconductor package of Claim 29 wherein the molding compound comprises a resin.

34. (Cancelled)

35. (Previously Presented) The semiconductor package of Claim 29 wherein:
the lower surface of the molding compound extends along a first plane;
the lower surfaces of the bonding pads extend along a common second plane; and
the first and second planes extend in spaced, generally parallel relation to each other.
36. (Cancelled)
37. (Currently Amended) The semiconductor package of Claim ~~36~~ 35 wherein the lower surface of the die pad extends along the second plane.
38. (Previously Presented) The semiconductor package of Claim 29 wherein:
the upper surface of the die pad is generally planar; and
the upper surfaces of the bonding pads are generally planar and extend in generally co-planar relation to the upper surface of the die pad.
39. (Currently Amended) A semiconductor package, comprising:
a leadframe having a plurality of homogeneous bonding pads defining opposed upper and lower surfaces;
a die electrically connected to at least one of the bonding pads; and
a molding compound at least partially encapsulating the die and the leadframe such that portions of the bonding pads which define the lower surfaces thereof protrude from a lower surface of the molding compound;
wherein the leadframe is subjected to a metal removal process which electrically isolates the bonding pads from each other, and exposes the lower surface of the molding compound.
40. (Previously Presented) The semiconductor package of Claim 39 wherein the leadframe further comprises a homogeneous die pad defining opposed upper and lower surfaces, the die being attached to the upper surface of the die pad.
41. (Previously Presented) The semiconductor package of Claim 40 wherein the die is attached to the upper surface of the die pad through the use of an adhesive material.
42. (Previously Presented) The semiconductor package of Claim 40 wherein:
the lower surface of the molding compound extends along a first plane;

the lower surfaces of the bonding pads extend along a common second plane;

the lower surface of the die pad extends along the second plane; and

the first and second planes extend in spaced, generally parallel relation to each other.

43. (Previously Presented) The semiconductor package of Claim 39 wherein the die is electrically connected to the bonding pads via bonding wires which are encapsulated by the molding compound.

44. (Currently Amended) A semiconductor package, comprising:

a leadframe having:

a homogeneous die pad defining opposed upper and lower surfaces; and

at least one homogeneous bonding pad disposed in spaced relation to the die pad and defining opposed upper and lower surfaces;

a die attached to the upper surface of the die pad and electrically connected to the bonding pad; and

a molding compound at least partially encapsulating the die and the leadframe such that ~~a portion~~ portions of the at least one bonding pad and the die pad which ~~defines~~ define the lower surface surfaces thereof ~~protrudes~~ protrude from a lower surface of the molding compound;

wherein the leadframe is subjected to a metal removal process which electrically isolates the at least one bonding pad and the die pad from each other, and exposes the lower surface of the molding compound.

45. (Previously Presented) The semiconductor package of Claim 44 wherein the die is electrically connected to the bonding pad via a bonding wire which is encapsulated by the molding compound.

46. (Previously Presented) The semiconductor package of Claim 44 wherein:

the lower surface of the molding compound extends along a first plane;

the lower surface of the bonding pad extends along a second plane; and

the first and second planes extend in spaced, generally parallel relation to each other.

47. (Cancelled)

48. (Currently Amended) The semiconductor package of Claim 47 46 wherein the lower surface of the die pad extends along the second plane.

49. (New) The semiconductor package of Claim 29 wherein the metal removal process is accomplished by chemically etching the leadframe.

50. (New) The semiconductor package of Claim 39 wherein the metal removal process is accomplished by chemically etching the leadframe.

51. (New) The semiconductor package of Claim 44 wherein the metal removal process is accomplished by chemically etching the leadframe.